



(51) International Patent Classification:
H01L 21/311 (2006.01) *G03F 7/42* (2006.01)
B41J 2/16 (2006.01)

(21) International Application Number:
PCT/AU2009/001088

(22) International Filing Date:
25 August 2009 (25.08.2009)

(25) Filing Language: English

(26) Publication Language: English

(71) Applicant (for all designated States except US): **SILVERBROOK RESEARCH PTY LTD** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **FU, Yao** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **TSAI, Yi-Wen** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **MCREYNOLDS, Darrell LaRue** [US/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **SECKER, David** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **BORDELANNE, Valerie** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU). **WISZNIEWSKI, Witold** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU).

(74) Agent: **SILVERBROOK RESEARCH PTY LTD**; 393 Darling Street, Balmain, New South Wales 2041 (AU).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))

(54) Title: METHOD OF REMOVING PHOTORESIST AND ETCH-RESIDUES FROM VIAS

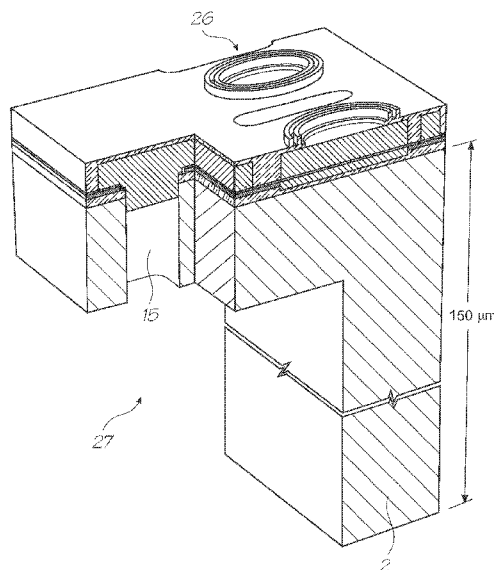


FIG. 18

(57) Abstract: A method of photoresist removal with concomitant de-veiling is provided. The method employs a plasma formed from a gas chemistry comprising O₂, NH₃ and a fluorine-containing gas, such as CF₄. The method is particularly suitable for use in MEMS fabrication processes, such as inkjet printhead fabrication.

